ABSTRACT OF DISCLOSURE

An integrated circuit package is provided. The package includes a substrate having first and second surfaces and a plurality of conductive traces therebetween. The substrate further has a cavity therein and a heat slug is fixed to the substrate and spans the cavity. A semiconductor die is mounted to the heat slug such that at least a portion of the semiconductor die is disposed in the cavity. A plurality of wire bonds connect the semiconductor die to ones of the conductive traces of the substrate and an encapsulating material encapsulates the wire bonds and the semiconductor die. A ball grid array is disposed on the first surface of the substrate. Bumps of the ball grid array are in electrical connection with ones of the conductive traces.